## In The Claims

Please rewrite Claim 1, cancel Claim 2 and add Claims 18-19 as follows:

1. (Currently amended) An etching agent for etching copper in an etching process comprising-in an aqueous solution containing consisting essentially of potassium hydrogen peroxomonosulfate and acetic acid, a concentration of said potassium hydrogen peroxomonosulfate falling within a range of 10.01% to about 23.31% by weight of the etching agent, said etching agent etching the copper at an approximately uniform rate throughout the etching process.

Claims 2-3 and 13-16 (Cancelled)

- 4. (Withdrawn) An etching agent for a laminated film of a titanium film and a copper film comprising an aqueous solution containing potassium hydrogen peroxomonosulfate and hydrofluoric acid.
- 5. (Withdrawn) An etching agent for a laminated film of a molybdenum film and a copper film comprising an aqueous solution containing potassium hydrogen peroxomonosulfate, phosphoric acid and nitric acid.
- 6. (Withdrawn) An etching agent for a laminated film of a chromium film and a copper film comprising an aqueous solution containing potassium hydrogen peroxomonosulfate and hydrochloric acid.
- 7. (Withdrawn) An etching agent for a laminated film of a titanium film and a copper film comprising an aqueous solution containing a peroxomonosulfate salt, hydrofluoric acid, and hydrochloric acid or a chloride.
- 8. (Withdrawn) An etching agent for a laminated film of a titanium film and a copper film comprising an aqueous solution containing a peroxosulfate salt and a fluoride.

- 9. (Withdrawn) An etching agent for a laminated film of a titanium film and a copper film according to Claim 7, wherein said peroxosulfate salt comprises any one or more compounds selected from KHSO<sub>5</sub>, NaHSO<sub>5</sub>, K<sub>2</sub>S<sub>2</sub>O<sub>8</sub>, Na<sub>2</sub>S<sub>2</sub>O<sub>8</sub> and (NH<sub>4</sub>)<sub>2</sub>S<sub>2</sub>O<sub>8</sub>.
- 10. (Withdrawn) An etching agent for a laminated film of a titanium film and a copper film according to Claim 7, wherein said chloride comprises an alkali metal chloride or ammonium chloride.
- 11. (Withdrawn) An etching agent for a laminated film of a titanium film and a copper film according to Claim 8, wherein said peroxosulfate salt comprises any one or more compounds selected from KHSO<sub>5</sub>, NaHSO<sub>5</sub>, K<sub>2</sub>S<sub>2</sub>O<sub>8</sub>, Na<sub>2</sub>S<sub>2</sub>O<sub>8</sub> and (NH<sub>4</sub>)<sub>2</sub>S<sub>2</sub>O<sub>8</sub>.
- 12. (Withdrawn) An etching agent for a laminated film of a titanium film and a copper film according to Claim 8, wherein said fluoride comprises an alkali metal fluoride or ammonium fluoride.
- 17. (Previously presented) An etching agent according to claim 1, wherein said etching agent is capable of selectively etching the copper.
- 18. (New) An etching agent for etching copper in an etching process in an aqueous solution consisting essentially of potassium hydrogen peroxomonosulfate, a concentration of said potassium hydrogen peroxomonosulfate falling within a range of 10.01% to about 23.31% by weight of the etching agent, said etching agent etching the copper at an approximately uniform rate throughout the etching process.
- 19. (New) An etching agent according to claim 17, wherein said etching agent is capable of selectively etching the copper.